



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS3205G		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000384017						
<b>Package</b>		PG-DSO-8-24		<b>Weight*</b>		82.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.717	0.87	0.87	8656	8656
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8660	
wire	non noble metal	copper	7440-50-8	29.121	35.16	36.08	351615	360816
	noble metal	gold	7440-57-5	0.243	0.29	0.29	2929	2929
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1211
encapsulation	plastics	epoxy resin	-	4.612	5.57		55691	
	inorganic material	silicondioxide	60676-86-0	45.422	54.84	60.53	548433	605335
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9826	9826
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7851	7851
glue	plastics	epoxy resin	-	0.066	0.08		803	
	noble metal	silver	7440-22-4	0.313	0.38	0.46	3784	4587
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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